

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S629	38	(partition or wall or bod\$3) (module or components) resin (metal or conductive) near (first and second)	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/07 18:50
S630	48	(partition or wall or bod\$3) (module or components) resin (metal or conductive) near (first and second)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/07 18:51
S631	98	(partition or wall or bod\$3) (module or components or chips) resin (metal or conductive) near (first and second)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/07 18:51
S632	555214	module	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/07 18:53
S633	264847	module (circuit or component)	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/07 18:54
S634	25324	module (circuit or component)(conductive or foil or metal)	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/07 18:54
S635	4656	module (circuit or component)(conductive or foil or metal)(resin or ceramic or epoxy)	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/07 18:55
S636	663	module (circuit or component)(conductive or foil or metal)(resin or ceramic or epoxy)(first and second)	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/07 18:56
S637	412	module (circuit or component)(conductive or foil or metal)(resin or ceramic or epoxy)(first and second)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/07 18:56
S638	68	module (circuit or component)(conductive or foil or metal)(resin or ceramic or epoxy)(first and second)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/07 18:56
S639	93	module (circuit or component or chip)(conductive or foil or metal)(resin or ceramic or epoxy)(first and second)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/07 19:48
S640	7	("5311059" "5355016" "5461545" "5541448" "5600181" "5601675" "5694300").PN. OR ("7180012").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/07 18:59
S641	31	("4040874" "4477828" "4768081" "5302553" "5332921" "5461545").PN. OR ("5600181").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/07 19:00
S642	13	("5168344" "5280413" "5315486" "5488256" "5497033" "5600181" "5751554" "5764484" "5834705" "5869894").PN. OR ("6018463").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/07 19:02

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S64 3	95	module (capacitor or circuit or component or chip)(conductive or foil or metal)(resin or ceramic or epoxy)(first and second)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/07 19:48
S64 4	149	module (capacitor or circuit or component or chip)(conductive or foil or metal)(resin or ceramic or epoxy)(first and second)	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/07 19:55
S64 5	7785301	(conductive or foil or metal) (metal or Cu) (resin or epoxy)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/07 19:59
S64 6	18144	(first and second)(conductive or foil or metal) (metal or Cu) (resin or epoxy)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/07 20:00
S64 7	6402	(first and second)(conductive or foil or metal) (metal or Cu) (resin or epoxy)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/07 20:00
S64 8	8	(first and second)(conductive or foil or metal) (metal or Cu) (resin or epoxy)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2007/11/07 20:05
S64 9	0	(first and second)near(foil or metal or Cu)near4 conductive (resin or epoxy)near6 conductive and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2007/11/07 20:06
S65 0	5	(first and second)near(foil or metal or Cu)near4 conductive (resin or epoxy)near6 conductive and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/07 20:08
S65 1	12	(first and second)near(foil or metal or Cu)near4 conductive (resin or epoxy)near6 conductive and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/07 20:08
S65 2	10507	(first and second)(conductive or foil or metal or Cu) (resin or epoxy)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 11:25

EAST Search History

S65 3	1128	(first and second)near(conductive or foil or metal or Cu) (resin or epoxy)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 11:25
S65 4	1128	(first and second)near(conductive or foil or metal or Cu) with (resin or epoxy)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 11:26
S65 5	1867	(first and second)near(conductive or foil or metal or Cu) with (adhesive or resin or epoxy)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 11:26
S65 6	102	(first and second)near(conductive near adhesive)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 11:28
S65 7	9	(first and second)near(metal and conductive(resin or adhesive))and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 11:31
S65 8	0	(first and second)near(metal with conductive(resin))and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 11:31
S65 9	45	(first and second)near(metal with(resin))and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 11:32
S66 0	3	"6884938"	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 12:07
S66 1	5570388	conductive near (metal or foil or film) separat\$3 (wall or partition or stiffner or resin or ceramic)	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 12:08
S66 2	3504	conductive near (metal or foil or film) separat\$3 (wall or partition or stiffner or resin or ceramic)	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/08 12:09

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S66 3	571	conductive near (metal or foil or film) separat\$3 (wall or partition or stiffner or resin or ceramic)	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/08 12:09
S66 4	416	conductive near (metal or foil or film) separat\$3 (wall or partition or stiffner or resin or ceramic)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/08 12:19
S66 5	515	conductive near (metal or foil or film) separat\$3 (groove or wall or partition or stiffner or resin or ceramic)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/08 12:20
S66 6	291	conductive near (metal or foil or film) separat\$3 (groove or wall or partition)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/08 12:30
S66 7	164	conductive near (metal or foil or film) separat\$3 (wall or partition)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/08 13:30
S66 8	87	conductive near (metal or foil) separat\$3 (wall or partition)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/08 16:33
S66 9	6142	(metal or foil) separat\$3 (wall or partition)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/08 13:32
S67 0	120	(metal or foil) separat\$3 (wall or partition)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	NEAR	ON	2007/11/08 13:32
S67 1	0	(first or second or multiple or multi\$layer) (metal or foil) separat\$3 (wall or partition)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	NEAR	ON	2007/11/08 13:33
S67 2	1	(first or second or multiple or multi\$layer) (metal or foil) separat\$3 (wall or partition)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2007/11/08 13:34
S67 3	17	(first or second or multiple or multi\$layer) near (metal or foil) adj (film or layer or laminate) separat\$3 (wall or partition)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 13:36
S67 4	8	"0702541"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/08 13:37
S67 5	1	"07022541"	JPO	OR	ON	2007/11/08 13:37
S67 6	1	"09061456"	JPO	OR	ON	2007/11/08 13:38

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S67 7	1	"11150208"	JPO	OR	ON	2007/11/08 13:38
S67 8	1	"09008487"	JPO	OR	ON	2007/11/08 13:39
S67 9	1	"06097694"	JPO	OR	ON	2007/11/08 13:39
S68 0	1	"02246199"	JPO	OR	ON	2007/11/08 13:40
S68 1	1	"06252291"	JPO	OR	ON	2007/11/08 13:40
S68 2	0	"060132547"	JPO	OR	ON	2007/11/08 13:40
S68 3	1	"06132547"	JPO	OR	ON	2007/11/08 13:41
S68 4	1	"59028363"	JPO	OR	ON	2007/11/08 13:43
S68 5	0	"63131196"	JPO	OR	ON	2007/11/08 13:44
S68 6	0	"111550391"	JPO	OR	ON	2007/11/08 13:44
S68 7	1	"11150391"	JPO	OR	ON	2007/11/08 13:45
S68 8	905946	conductive film	JPO	OR	ON	2007/11/08 13:45
S68 9	20303	conductive film	JPO	NEAR	ON	2007/11/08 13:45
S69 0	575	(first and second)conductive film	JPO	NEAR	ON	2007/11/08 13:45
S69 1	0	(first and second)conductive film partition	JPO	NEAR	ON	2007/11/08 13:45
S69 2	0	(first and second)conductive film groove	JPO	NEAR	ON	2007/11/08 13:45
S69 3	30	(first and second)conductive film same groove	JPO	NEAR	ON	2007/11/08 14:30
S69 4	58	(first and second)conductive film same wall	JPO	NEAR	ON	2007/11/08 14:31
S69 5	440	(first and second)conductive film same wall	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2007/11/08 14:33
S69 6	0	(first and second)conductive film same wall module	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2007/11/08 14:33
S69 7	0	(first and second)foil film same wall module	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2007/11/08 14:33

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S69 8	0	(first and second)foil same wall module	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2007/11/08 14:33
S69 9	47	(first and second)foil same wall module	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 14:34
S70 0	25	(first and second)foil same wall module and @ad<"20040430"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 14:34
S70 1	25	(first and second)foil same wall module and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 14:35
S70 2	780	(first and second)conduc\$4 same wall module and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 14:36
S70 3	5	"6873059"	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 14:43
S70 4	17	"5073817"	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 14:44
S70 5	8	"6301122"	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 14:49
S70 6	0	(device or capacitor or circuit or chip or radio)near module same (encapsulat\$3 or resin or ceramic or epoxy) same (first or second or third or fourth)adj (film or layer) near (copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 14:52
S70 7	42	(device or capacitor or circuit or chip or radio)near module and (encapsulat\$3 or resin or ceramic or epoxy) same (first or second or third or fourth)adj (film or layer) near (copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 14:57
S70 8	0	("2007/0080447").URPN.	USPAT	OR	ON	2007/11/08 14:55
S70 9	43	(device or capacitor or circuit or chip or radio or electric\$2)near module and (encapsulat\$3 or resin or ceramic or epoxy) same (first or second or third or fourth)adj (film or layer) near (copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 14:58

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S71 0	43	(device or capacitor or circuit or chip or radio or electric\$2)near module and (encapsulat\$3 or resin or ceramic or epoxy) same (first or second or third or fourth)adj (film or layer) near (copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/08 14:59
S71 1	766	(device or capacitor or circuit or chip or radio or electric\$2)and (encapsulat\$3 or resin or ceramic or epoxy) same (first or second or third or fourth)adj (film or layer) near (copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/08 15:08
S71 2	766	(device or capacitor or circuit or chip or radio or electric\$2) and (encapsulat\$3 or resin or ceramic or epoxy) same (first or second or third or fourth)adj (film or layer) near (copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/08 15:00
S71 3	670564	(device or capacitor or circuit or chip or radio or electric\$2) with (encapsulat\$3 or resin or ceramic or epoxy) same (first or second or third or fourth)or (film or layer) near (copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/08 15:12
S71 4	1080316	(encapsulat\$3 or resin or ceramic or epoxy) same (first or second or third or fourth)or (film or layer) near (copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 15:13
S71 5	99210	(encapsulat\$3 or resin or ceramic or epoxy) same (film or layer) near (copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 15:14
S71 6	366911	(encapsulat\$3 or resin or ceramic or epoxy) same (film or layer)(copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 15:14
S71 7	280911	(encapsulat\$3 or resin or ceramic or epoxy) same (film or layer)(copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 15:14
S71 8	199451	(encapsulat\$3 or resin or ceramic or epoxy) (film or layer)(copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 15:14

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S71 9	11332	(encapsulat\$3 or resin or ceramic or epoxy) (film or layer)(copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2007/11/08 15:15
S72 0	4952	(encapsulat\$3 or resin or ceramic or epoxy) (film or layer)(copper or cu or conductive or metal or foil)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/11/08 15:15
S72 1	12	("20050168106" "20060066178" "20060279173" "5237239" "5607535" "6106106" "6502302" "6637102" "6700306" "6731050" "7061162" "7148607").PN. OR ("7274134").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/08 15:18
S72 2	87	wall same circuit blocks and @py<"2004"	US-PGPUB; USPAT	ADJ	ON	2007/11/08 15:27
S72 3	252	(first and second)near shield with wall	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 15:29
S72 4	199	(first and second)near shield with wall and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 15:31
S72 5	389279	(first and second)near shield with wall module and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 15:31
S72 6	8	(first and second)near shield with wall module and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/08 15:32
S72 7	10	(first and second)near (shield or metal or foil) with wall module and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/08 15:33
S72 8	10	(first and second)near (shield or metal or foil) with wall module and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 15:34
S72 9	1568	(shield or metal or foil) with wall module and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/08 15:34
S73 0	174	(shield or metal or foil) with wall module and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2007/11/08 15:34

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S73 1	0	("2007/0080447").URPN.	USPAT	OR	ON	2007/11/08 15:43
S73 2	7	"6744135"	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 15:45
S73 3	5	("6020629" "6528882").PN. OR ("6744135").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/08 15:45
S73 4	205	("4505799" "4996587" "5063177" "5107328" "5138434" "5155067" "5229647" "5266912" "5334857" "5384689" "5444296" "5468999" "5474957" "5562971" "5633530" "5646828" "5674785" "5677566" "5689091" "5696033" "5723900" "5739585" "5753857" "5763939" "5796038" "5811879").PN. OR ("6020629").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/08 15:49
S73 5	77192	separa\$4 (wall or groove or partition)	US-PGPUB; USPAT; USOCR; FPRS	NEAR	ON	2007/11/08 15:50
S73 6	42627	separa\$4 (wall or groove or partition)	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 15:50
S73 7	28	separa\$4 (wall or groove or partition)same (seal\$3 or resin or epoxy)(body)	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 15:53
S73 8	284	separa\$4 (wall or groove or partition)same (seal\$3 or resin or epoxy)(body or member)	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 15:53
S73 9	200	separa\$4 near6(wall or groove or partition)near6(seal\$3 or resin or epoxy)(body or member)	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 15:59
S74 0	11370	(wall or groove or partition)near6(seal\$3 or resin or epoxy)(body or member)	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 16:11
S74 1	21083	module component	US-PGPUB; USPAT; USOCR; FPRS	NEAR	ON	2007/11/08 16:12
S74 2	13310	module component and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	NEAR	ON	2007/11/08 16:12
S74 3	6118	module component and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 16:12
S74 4	105	module component.ti. and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	NEAR	ON	2007/11/08 16:13
S74 5	10	("5153379" "5166772" "5311059" "6049469" "6388535" "6469380" "6483175" "6487088" "6512183" "6585149").PN. OR ("7161252").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/08 16:18

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S74 6	8	("5874043" "6010060" "6116497" "6364195").PN. OR ("6585149").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/08 16:21
S74 7	7	("2440709" "4985687" "5306948" "5952898" "6456168").PN. OR ("6674221").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/08 16:25
S74 8	4	("5382929").PN. OR ("5952898").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/08 16:25
S74 9	7	("2440709" "4985687" "5306948" "5952898" "6456168").PN. OR ("6674221").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/08 16:32
S75 0	17	("4609883" "5265316" "5438219" "5500628" "6229249" "6229404" "6239669").PN. OR ("6456168").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/08 16:27
S75 1	29958	first conductive film	US-PGPUB; USPAT; USOCR; FPRS	WITH	ON	2007/11/08 16:33
S75 2	4031	first conductive film	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 16:33
S75 3	3	first conductive film (partition or wall)	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 16:34
S75 4	339	first conductive film with(partition or wall)	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:12
S75 5	5454	(conductive and resin) film	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:13
S75 6	3554	(conductive and resin) film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:17
S75 7	206	(conductive near resin) film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:18
S75 8	144	(metal near resin) film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:19
S75 9	0	(metal near conductive adj resin) film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:20
S76 0	3	(metal near4 conductive adj resin) film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:21
S76 1	59	(metal near4 conductive near4 resin) film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:22

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S76 2	35	(metal near4 conductive near4 laminat\$2) film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:24
S76 3	47	(conductive epoxy) film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:27
S76 4	0	(conductive epoxy) film device modules and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:28
S76 5	0	(conductive epoxy) film with device modules and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:28
S76 6	0	(conductive epoxy) film with device modules and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	ADJ	ON	2007/11/08 18:29
S76 7	1	"6936407"	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 18:36
S76 8	5663115	conductive near2 adhesive adj film connect\$4 ground	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2007/11/08 18:38
S76 9	19	conductive near2 adhesive adj film connect\$4 ground	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/08 18:46
S77 0	6	conductive adj adhesive adj film connect\$4 ground	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/08 18:47
S77 1	514	conductive adj adhesive adj film	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/08 18:57
S77 2	407	conductive adj adhesive adj film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/08 18:58
S77 3	17	conductive adj adhesive adj interconnect and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/08 19:02
S77 4	55	conductive adj adhesive adj connect and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/08 19:05
S77 5	0	conductive adj adhesive adj film periphery (encapsulate or seal\$3 adj member) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS	SAME	ON	2007/11/08 19:06

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S77 6	0	conductive adj adhesive adj film periphery (encapsulate or seal\$3 adj member) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:06
S77 7	6	conductive adj adhesive adj film (encapsulate or seal\$3 adj member) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:10
S77 8	152	conductive adj adhesive adj film (encapsulate or resin or seal\$3 adj member) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:19
S77 9	0	conductive adj adhesive adj film on (encapsulate or resin or seal\$3 adj member) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:19
S78 0	23	conductive adj adhesive adj film above (encapsulate or resin or seal\$3 adj member) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:24
S78 1	1	conductive adj adhesive adj film periphery device and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:26
S78 2	134	conductive adj adhesive adj film device and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:30
S78 3	629	conductive adj adhesive adj (film or shield) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:30
S78 4	4	conductive adj adhesive adj (film or shield) circuit blocks and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:31

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S78 5	4	conductive adj adhesive adj film circuit blocks and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:31
S78 6	9	conductive adj adhesive adj film blocks and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:32
S78 7	626	conductive adj adhesive adj film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:33
S78 8	366	conductive adj resin adj film and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:34
S78 9	680	conductive adj adhesive adj(film or lid or cover) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:34
S79 0	67	conductive adj epoxy adj(film or lid or cover) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:35
S79 1	57	conductive adj epoxy adj(film or lid) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:35
S79 2	4	conductive adj epoxy adj(lid) and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2007/11/08 19:35
S79 3	3586	conductive (resin or polymer or adhesive or epoxy or polypropylen or polystyren or PES or PEEK)(film or electrode or interconnect)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/11/09 08:56

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S79 4	2893	conductive (resin or polymer or adhesive or epoxy or polypropylen or polystyren or PES or PEEK)(film or electrode or interconnect)and @ad<"20040330"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/11/09 08:59
S79 5	2	conductive (resin or polymer or adhesive or epoxy or polypropylen or polystyren or PES or PEEK)(film or electrode or interconnect)and @ad<"20040330" and 257/E23.002.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/11/09 09:00
S79 6	2	conductive (resin or polymer or adhesive or epoxy or polypropylen or polystyren or PES or PEEK)(film or electrode)and @ad<"20040330" and 257/E23.002.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/11/09 09:01
S79 7	28	conductive (resin or polymer or adhesive or epoxy or polypropylen or polystyren or PES or PEEK)and @ad<"20040330" and 257/E23.002.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/11/09 09:02
S79 8	1	conductive adj(resin or polymer or adhesive or epoxy or polypropylen or polystyren or PES or PEEK)(hous\$3 or lid)and @ad<"20040330" and 257/E23.002.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/09 09:05
S79 9	20	conductive adj(resin or polymer or adhesive or epoxy or polypropylen or polystyren or PES or PEEK)(layer or lid)and @ad<"20040330" and 257/E23.002.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/09 09:08
S80 0	240	conductive adj(resin or polymer or adhesive or epoxy or polypropylen or polystyren or PES or PEEK)(layer or lid)and @ad<"20040330" and 257/E21.502-e21.504.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/09 09:13
S80 1	412	conductive adj(resin or polymer or adhesive or epoxy or polypropylen or polystyren or PES or PEEK)and module and @ad<"20040330" and 257/E21.502-e21.504.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/09 09:27
S80 2	1112	module and @ad<"20040330" and 257/E21.502-e21.504.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2007/11/09 09:27